

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)	
	:	Examiner: B. K. Talbot
MICHINORI SHINKAI, ET AL.)	
	:	Group Art Unit: 1715
Application No.: 10/582,920)	
	:	Confirmation No.: 9223
Filed: June 13, 2006)	
	:	December 21, 2010
For: WIRE FORMING METHOD)	

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

STATEMENT OF SUBSTANCE OF INTERVIEW

Sir:

Applicants wish to thank the Examiner for the courtesies extended toward their representative during the personal interview of January 19, 2011.

The interview focused primarily on independent Claim 23 and the Furusawa '305 patent and Lee '657 publication.

No agreement was reached at the interview. However, differences between the subject application and the wiring board production method in Furusawa were discussed. For example, the conductive wiring pattern 17 and insulating layer 21 in Furusawa are formed in multi-planar layers.

It was agreed that Applicants would respond to the final Office Action in due course.

It is respectfully submitted that this Statement is a complete and accurate summary of the interview.

It is believed that no fee is required for this Statement. However, the Commissioner is hereby authorized to charge any fee which may be deemed necessary in connection with this paper to Deposit Account No. 06-1205.

Applicants' undersigned attorney may be reached in our Washington, D.C. office by telephone at (202) 530-1010. All correspondence should continue to be directed to our address given below.

Respectfully submitted,

/Scott D. Malpede/

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